

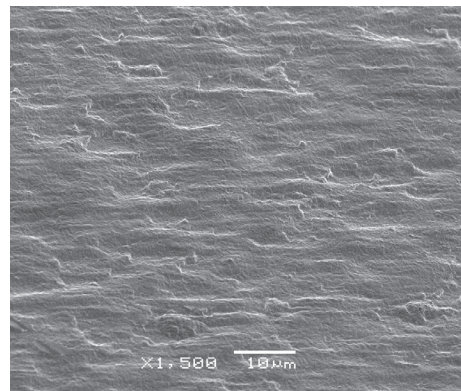
General purpose electrodeposited copper foil used in applications where traditional conductive treatments are not required.

**Applications:**

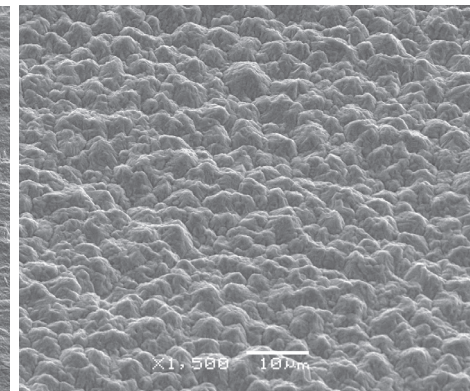
- EMI & RF Shielding
- Industrial use

**Features:**

- IPC Grade I
- No oils or organic coatings
- Available up to 1346 mm (53”) wide



Untreated Drum Side  
H oz. /18 µm (1500x)



Untreated Matte Side  
H oz. /18 µm (1500x)

**Typical Values:**

Attribute		Unit	Value							Reference
Thickness Designation			H	1	2	3	4	5	6	IPC-4562, 1.2.5.1 Table 1-1; IPC-TM-650-2.2.12
Nominal Thickness		µm	18	35	70	103	137.2	171.5	205.7	
		oz.	1/2	1	2	3	4	5	6	
Area Weight		g/m <sup>2</sup>	152.5	305	610	915	1,220	1,525	1,830	
		g/254 in <sup>2</sup>	25	50	100	150	200	250	300	
		oz./ft <sup>2</sup>	0.5	1	2	3	4	5	6	
Roughness	Drum Side Ra	µm	0.25							IPC-TM-650-2.2.17
		µ"	10							
	Matte Side Rz	µm	0.5	0.8	1.4	2.3	2.7	3.3	3.8	
		µ"	20	30	55	90	105	130	150	
Tensile	Ambient	Kg/mm <sup>2</sup>	42.2	38.7	36.9	35.2	33.4	31.7	31.7	IPC-TM-650-2.4.18
		Kpsi	60	55	53	50	48	45	45	
Elongation	Ambient	%	8	15	20	25	28	30	30	

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